

**Amendments to the Claims:**

1. (Currently Amended) A method of fabricating a memory card, comprising the steps of:

- a) providing a leadframe having:
  - ~~a dambar; and~~
  - a plurality of contacts defining opposed top and bottom contact surfaces, ~~each of the contacts being attached to the dambar by at least one tie bar;~~
- b) electrically connecting at least one semiconductor die to the leadframe;
- c) forming a first body section on the leadframe which **at least partially** encapsulates the semiconductor die and ~~at least a~~ **first** portion of the leadframe;
- ~~d) removing the dambar and the tie bars from the leadframe; and~~
- e) **d)** forming a second body section on the leadframe which **at least** partially encapsulates ~~the contacts~~ **a second portion of the leadframe, the first and second body sections being formed** such that at least portions of the bottom contact surfaces of the contacts are exposed in an exterior surface of **a memory card body collectively defined by the first and** second body sections.

2. (Currently Amended) The method of Claim 1 wherein:

- step (a) comprises providing a leadframe having a die pad which defines opposed top and bottom die pad surfaces ~~and is attached to the dambar;~~
- step (b) comprises attaching the semiconductor die to the top die pad surface of the die pad; and
- step (c) comprises forming the first body section to at least partially ~~encapsulates~~ **encapsulate** the die pad.

3. (Currently Amended) The method of Claim 2 wherein:

- step (a) comprises providing a leadframe having a plurality of conductive traces which extend from respective ones of the contacts toward the die pad;
- step (b) comprises electrically connecting the semiconductor die to at least one of the conductive traces; and

step (c) comprises forming the first body section such that the conductive traces are **at least partially** encapsulated thereby.

4. (Original) The method of Claim 3 wherein step (a) comprises providing a leadframe which is partially etched such that each of the conductive traces has a trace thickness which is less than a contact thickness of each of the contacts and a die pad thickness of the die pad.

5. (Original) The method of Claim 3 wherein step (a) comprises providing a leadframe wherein the conductive traces are bent such that the die pad and the contacts extend along respective ones of spaced, generally parallel planes.

6. (Currently Amended) The method of Claim 3 wherein step (c) comprises forming the first body section such that the die pad, the semiconductor die and the traces are **at least partially** encapsulated thereby, and **at least portions of** the contacts protrude from a common side surface thereof.

7. (Currently Amended) The method of Claim 1 wherein:

step (a) comprises providing a leadframe wherein the bottom contact surfaces of the contacts are each generally planar; and

~~steps (e) comprises~~ **(c) and (d)** comprise forming the **first and** second body sections such that the exterior surface ~~thereof~~ **of the memory card body** is generally planar and the bottom contact surfaces of the contacts are exposed in and substantially flush with the exterior surface.

8. (Currently Amended) The method of Claim 1 wherein step ~~(e)~~ **(d)** comprises forming the second body section to abut the first body section.

9. (Currently Amended) The method of Claim 8 wherein:

step (c) comprises forming the first body section to define a first sloped side surface; and

step ~~(e)~~ **(d)** comprises forming the second body section to define a second sloped side surface which is abutted against the first sloped side surface and has an angle complimentary thereto.

10. (Currently Amended and Withdrawn) The method of Claim 1 wherein:

~~steps (c) and (e)~~ step (a) comprises ~~forming the first and second body sections from a common plastic material~~ providing a leadframe which includes a dambar and wherein each of the contacts is attached to the dambar by at least one tie bar; and

step (c) comprises removing the dambar and the tie bars from the leadframe subsequent to forming the first body section.

11. (Original) A method of fabricating a memory card, comprising the steps of:
  - a) providing a leadframe having a plurality of contacts defining opposed top and bottom contact surfaces;
  - b) electrically connecting at least one semiconductor die to the leadframe;
  - c) forming a first body section on the leadframe which encapsulates the semiconductor die and a portion of the leadframe other than for the contacts thereof; and
  - d) forming a second body section on the leadframe which partially encapsulates the contacts such that at least portions of the bottom contact surfaces of the contacts are exposed in an exterior surface of the second body section.
12. (Original) The method of Claim 11 wherein:
  - step (a) comprises providing a leadframe having a die pad;
  - step (b) comprises attaching the semiconductor die to the die pad; and
  - step (c) comprises forming the first body section to at least partially encapsulate the die pad.
13. (Original) The method of Claim 12 wherein:
  - step (a) comprises providing a leadframe having a plurality of conductive traces which extend from respective ones of the contacts toward the die pad;
  - step (b) comprises electrically connecting the semiconductor die to at least one of the conductive traces; and
  - step (c) comprises forming the first body section such that the conductive traces are encapsulated thereby.
14. (Original) The method of Claim 13 wherein step (a) comprises providing a leadframe which is partially etched such that each of the conductive traces has a trace

thickness which is less than a contact thickness of each of the contacts and a die pad thickness of the die pad.

15. (Original) The method of Claim 13 wherein step (a) comprises providing a leadframe wherein the conductive traces are bent such that the die pad and the contacts extend along respective ones of spaced, generally parallel planes.

16. (Original) The method of Claim 13 wherein step (c) comprises forming the first body section such that the die pad, the semiconductor die and the traces are encapsulated thereby, and the contacts protrude from a common side surface thereof.

17. (Original) The method of Claim 11 wherein:

step (a) comprises providing a leadframe wherein the bottom contact surfaces of the contacts are each generally planar; and

step (d) comprises forming the second body section such that the exterior surface thereof is generally planar and the bottom contact surfaces of the contacts are exposed in and substantially flush with the exterior surface.

18. (Original) The method of Claim 11 wherein step (d) comprises forming the second body section to abut the first body section.

19. (Original) The method of Claim 18 wherein:

step (c) comprises forming the first body section to define a first sloped side surface; and

step (d) comprises forming the second body section to define a second sloped side surface which is abutted against the first sloped side surface and has an angle complimentary thereto.

20. (Original) The method of Claim 11 wherein steps (c) and (d) comprise forming the first and second body sections from a common plastic material.